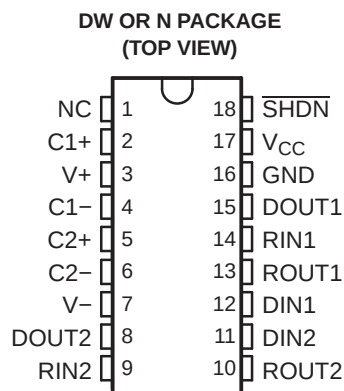


FEATURES

- ESD Protection for RS-232 Bus Pins
 - ± 15 -kV Human-Body Model (HBM)
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates at 5-V V_{CC} Supply
- Operates up to 200 kbit/s
- Low Supply Current in Shutdown Mode . . . 2 μ A Typical
- External Capacitors . . . $4 \times 0.1 \mu$ F
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II



APPLICATIONS

- Battery-Powered Systems
- PDAs
- Notebooks
- Laptops
- Palmtop PCs
- Hand-Held Equipment

DESCRIPTION/ORDERING INFORMATION

The TRS222 consists of two line drivers, two line receivers, and a dual charge-pump circuit with ± 15 -kV ESD protection pin to pin (serial-port connection pins, including GND). This device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 5-V supply. This device operates at data signaling rates up to 200 kbit/s and a maximum of 30-V/ μ s driver output slew rate. By using shutdown ($\overline{\text{SHDN}}$), all receivers can be disabled.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube of 20	TRS222CN	TRS222CN
	SOIC – DW	Tube of 20	TRS222CDW	TRS222C
		Reel of 1000	TRS222CDWR	
–40°C to 85°C	PDIP – N	Tube of 20	TRS222IN	TRS222IN
	SOIC – DW	Tube of 20	TRS222IDW	TRS222I
		Reel of 1000	TRS222IDWR	

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
- (2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

FUNCTION TABLES

Each Driver⁽¹⁾

INPUT DIN	OUTPUT DOUT
L	H
H	L

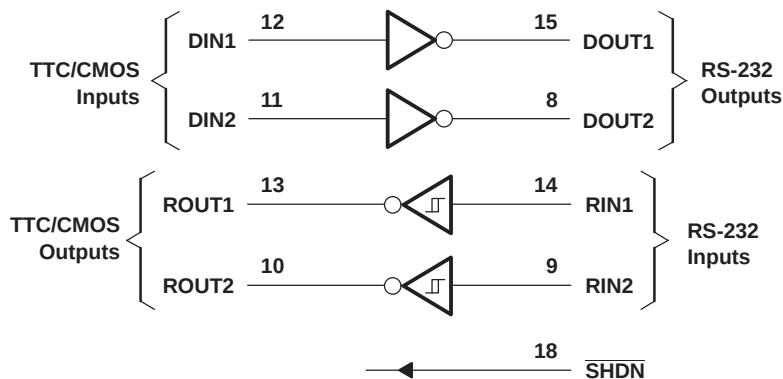
(1) H = high level, L = low level

Each Receiver⁽¹⁾

INPUT RIN	OUTPUT ROUT
L	H
H	L
Open	H

(1) H = high level, L = low level,
Open = input disconnected or
connected driver off

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range ⁽²⁾		–0.3	6	V
V_I	Input voltage range	Drivers	–0.3	$V_{CC} - 0.3$	V
		Receivers		± 30	
V_O	Output voltage range	Drivers		± 15	V
		Receivers	–0.3	$V_{CC} + 0.3$	
D_{OUT}	Short-circuit duration			Continuous	
θ_{JA}	Package thermal impedance ⁽³⁾⁽⁴⁾	DW package		58	°C/W
		N package		TBD	
T_J	Operating virtual junction temperature			150	°C
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltages are with respect to network GND.

(3) Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

See [Figure 4](#)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
V_{IH}	Driver high-level input voltage	DIN	2			V
	Shutdown high-level input voltage	$\overline{\text{SHDN}}$	2			
V_{IL}	Driver and control low-level input voltage	DIN			0.8	V
	Shutdown low-level input voltage	$\overline{\text{SHDN}}$			0.8	
V_I	Driver input voltage	DIN	0		5.5	V
	Receiver input voltage		–30		30	
T_A	Operating free-air temperature	TRS222C	0		70	°C
		TRS222I	–40		85	

(1) Test conditions are C1–C4 = 0.1 μF at $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$.

Electrical Characteristics⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{CC}	Supply current $V_{CC} = 5 \text{ V}$, $\overline{\text{SHDN}} = V_{CC}$	No load	4	10	mA
		3 k Ω on both inputs	15		
	Shutdown supply current		2	50	μA
$\overline{\text{SHDN}}$	Shutdown input leakage current			± 1	μA

(1) Test conditions are C1–C4 = 0.1 μF at $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$.

TRS222

5-V DUAL RS-232 LINE DRIVER/RECEIVER

WITH ± 15 -kV ESD PROTECTION

SLLS813–JULY 2007

DRIVER SECTION

Electrical Characteristics⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 4](#))

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V _{OH}	High-level output voltage	DOUT at R _L = 3 k Ω to GND, DIN = GND	5	8		V
V _{OL}	Low-level output voltage	DOUT at R _L = 3 k Ω to GND, DIN = V _{CC}	–5	–8		V
I _{IH}	Driver high-level input current	DIN = V _{CC}		5	40	μ A
	Control high-level input current	$\overline{\text{SHDN}}$ = V _{CC}		0.01	1	
I _{IL}	Driver low-level input current	DIN = 0 V		–5	–40	μ A
	Control low-level input current	$\overline{\text{SHDN}}$ = 0 V		–0.01	–1	
I _{OS}	Short-circuit output current ⁽³⁾	V _{CC} = 5.5 V, V _O = 0 V	± 7	± 22		mA
I _{off}	Output leakage current	V _{CC} = 5.5 V, $\overline{\text{SHDN}}$ = GND, V _O = ± 10 V		± 0.01	± 10	μ A
r _o	Output resistance	V _{CC} , V ₊ , and V _– = 0 V, V _O = ± 2 V	300	10 M		Ω

(1) Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 5 V $\pm$ 0.5 V.

(2) All typical values are at V_{CC} = 5 V, and T_A = 25°C.

(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

Switching Characteristics⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 4](#))

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
	Data rate	C _L = 1000 pF, R _L = 3 k Ω , One DOUT switching, See Figure 1	200			kbit/s
t _{PLH(D)}	Propagation delay time, low- to high-level output	See Figure 1		1.5	3.5	μ s
t _{PHL(D)}	Propagation delay time, high- to low-level output	See Figure 1		1.3	3.5	μ s
t _{PHL(D)} – t _{PLH(D)}	Driver (+ to –) propagation delay difference			300		ns
t _{sk(p)}	Pulse skew ⁽³⁾	C _L = 150 pF to 2500 pF, R _L = 3 k Ω to 7 k Ω , See Figure 2		300		ns
SR(tr)	Slew rate, transition region (see Figure 1)	C _L = 50 pF to 2500 pF, V _{CC} = 5 V, R _L = 3 k Ω to 7 k Ω	6	12	30	V/ μ s
t _{ET}	Driver output enable time (after $\overline{\text{SHDN}}$ goes high)			250		μ s
t _{DT}	Driver output disable time (after $\overline{\text{SHDN}}$ goes low)			300		ns

(1) Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 5 V $\pm$ 0.5 V.

(2) All typical values are at V_{CC} = 5 V, and T_A = 25°C.

(3) Pulse skew is defined as |t_{PLH} – t_{PHL}| of each channel of the same device.

RECEIVER SECTION

Electrical Characteristics⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 4](#))

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V _{OH} High-level output voltage	I _{OH} = –1 mA	3.5	V _{CC} – 0.2		V
V _{OL} Low-level output voltage	I _{OH} = 3.2 mA			0.4	V
V _{IT+} Positive-going input threshold voltage	V _{CC} = 5 V		1.7	2.4	V
V _{IT–} Negative-going input threshold voltage	V _{CC} = 5 V	0.8	1.3		V
V _{hys} Input hysteresis (V _{IT+} – V _{IT–})		0.2	0.5	1	V
r _i Input resistance	V _I = ± 3 V to ± 25 V	3	5	7	k Ω

(1) Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 5 V $\pm$ 0.5 V.

(2) All typical values are at V_{CC} = 5 V, and T_A = 25°C.

Switching Characteristics⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 3](#))

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
t _{PLH(R)} Propagation delay time, low- to high-level output	C _L = 150 pF		0.6	1	μ s
t _{PHL(R)} Propagation delay time, high- to low-level output	C _L = 150 pF		0.5	1	μ s
t _{PHL(R)} – t _{PLH(R)} Receiver (+ to –) propagation delay difference			100		ns
t _{sk(p)} Pulse skew ⁽³⁾			100		ns

(1) Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 5 V $\pm$ 0.5 V.

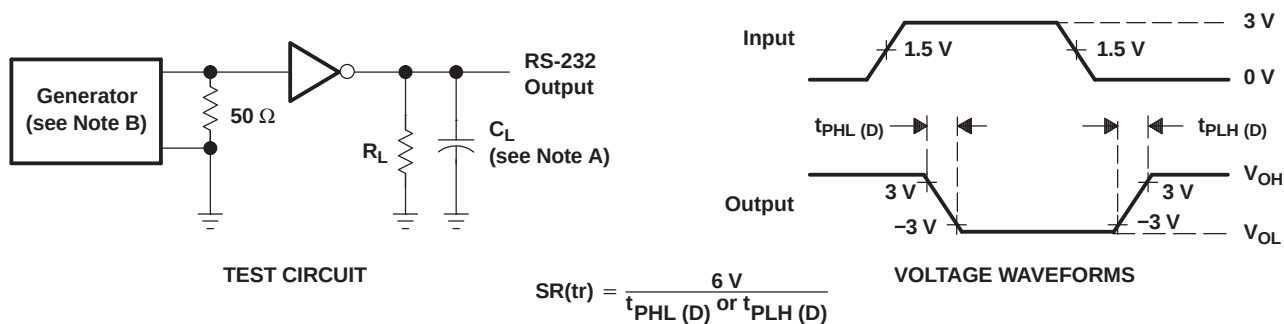
(2) All typical values are at V_{CC} = 5 V, and T_A = 25°C.

(3) Pulse skew is defined as |t_{PLH} – t_{PHL}| of each channel of the same device.

ESD Protection

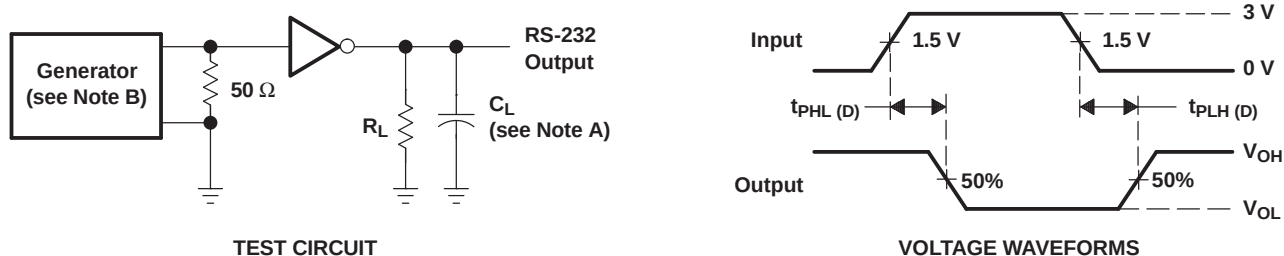
PIN	TEST CONDITIONS	TYP	UNIT
DOUT, RIN	Human-Body Model	± 15	kV

PARAMETER MEASUREMENT INFORMATION



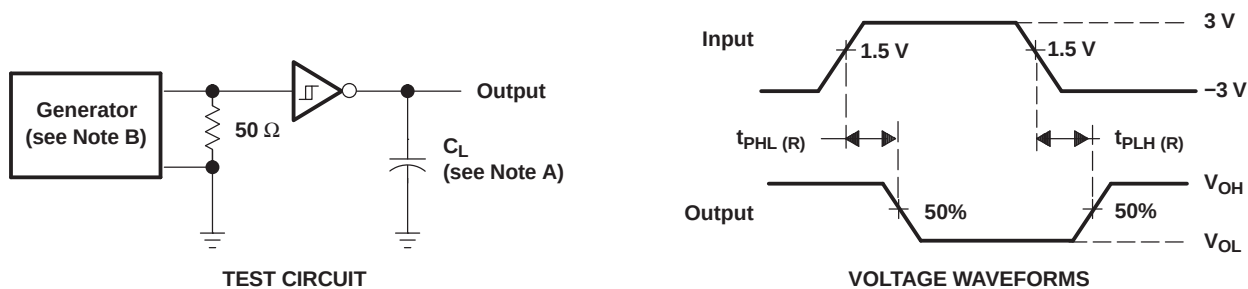
- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\ \text{ns}$, $t_f \leq 10\ \text{ns}$.

Figure 1. Driver Slew Rate



- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\ \text{ns}$, $t_f \leq 10\ \text{ns}$.

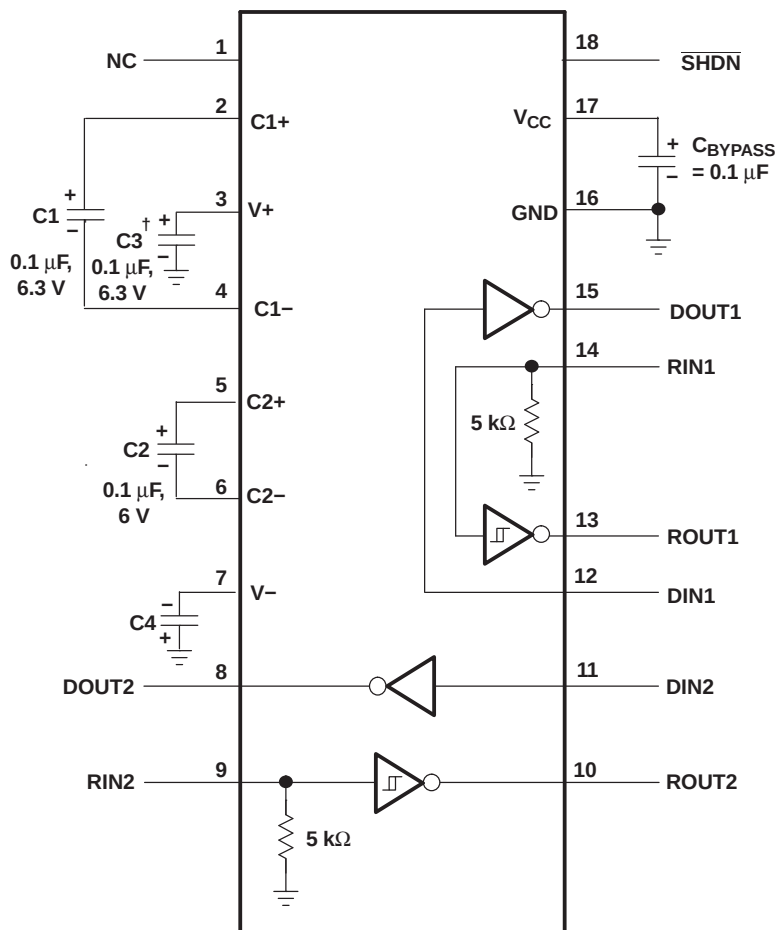
Figure 2. Driver Pulse Skew



- A. C_L includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\ \text{ns}$, $t_f \leq 10\ \text{ns}$.

Figure 3. Receiver Propagation Delay Times

APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.

- A. Resistor values shown are nominal
- B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

Figure 4. Typical Operating Circuit and Capacitor Values

APPLICATION INFORMATION (continued)

Capacitor Selection

The capacitor type used for C1–C4 is not critical for proper operation. The TRS222 requires 0.1- μ F capacitors, although capacitors up to 10 μ F can be used without harm. Ceramic dielectrics are suggested for the 0.1- μ F capacitors. When using the minimum recommended capacitor values, ensure that the capacitance value does not degrade excessively as the operating temperature varies. If in doubt, use capacitors with a larger (e.g., 2 $\times$) nominal value. The capacitors' effective series resistance (ESR), which usually rises at low temperatures, influences the amount of ripple on V+ and V–.

Use larger capacitors (up to 10 μ F) to reduce the output impedance at V+ and V–.

Bypass V_{CC} to ground with at least 0.1 μ F. In applications sensitive to power-supply noise generated by the charge pumps, decouple V_{CC} to ground with a capacitor the same size as (or larger than) the charge-pump capacitors (C1–C4).

Electrostatic Discharge (ESD) Protection

TI TRS222 devices have standard ESD protection structures incorporated on the pins to protect against electrostatic discharges encountered during assembly and handling. In addition, the RS-232 bus pins (driver outputs and receiver inputs) of these devices have an extra level of ESD protection. Advanced ESD structures were designed to successfully protect these bus pins against ESD discharge of ± 15 kV when powered down.

ESD Test Conditions

ESD testing stringently is performed by TI, based on various conditions and procedures. Contact TI for a reliability report that documents test setup, methodology, and results.

Human-Body Model (HBM)

The HBM of ESD testing is shown in Figure 5, while Figure 6 shows the current waveform that is generated during a discharge into a low impedance. The model consists of a 100-pF capacitor, charged to the ESD voltage of concern, and subsequently discharged into the DUT through a 1.5-k Ω resistor.

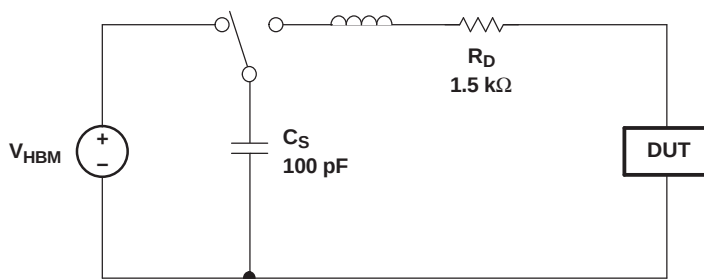


Figure 5. HBM ESD Test Circuit

APPLICATION INFORMATION (continued)

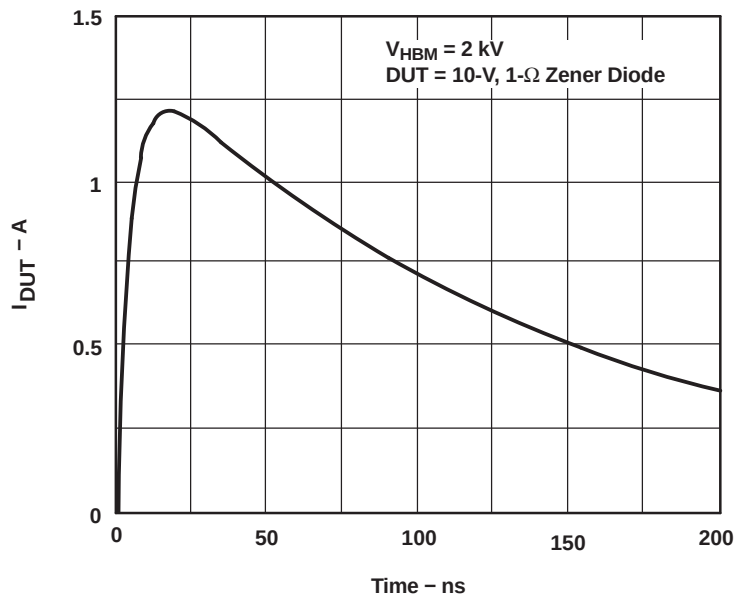


Figure 6. Typical HBM Current Waveform

Machine Model (MM)

The MM ESD test applies to all pins using a 200-pF capacitor with no discharge resistance. The purpose of the MM test is to simulate possible ESD conditions that can occur during the handling and assembly processes of manufacturing. In this case, ESD protection is required for all pins, not just RS-232 pins. However, after PC board assembly, the MM test no longer is as pertinent to the RS-232 pins.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
TRS222CDWR	ACTIVE	SOIC	DW	18	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
TRS222CDWRG4	ACTIVE	SOIC	DW	18	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
TRS222IDW	ACTIVE	SOIC	DW	18	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
TRS222IDWG4	ACTIVE	SOIC	DW	18	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
TRS222IDWR	ACTIVE	SOIC	DW	18	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
TRS222IDWRG4	ACTIVE	SOIC	DW	18	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
TRS222IN	ACTIVE	PDIP	N	18	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TRS222INE4	ACTIVE	PDIP	N	18	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and



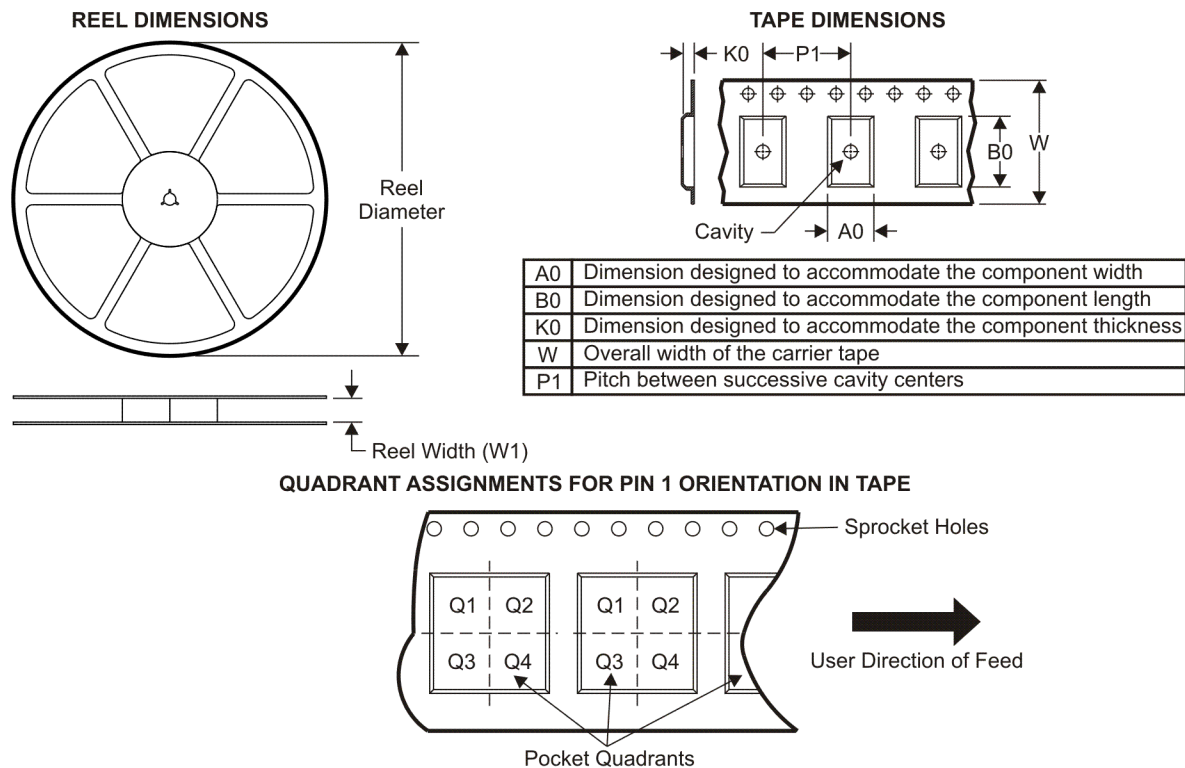
www.ti.com

PACKAGE OPTION ADDENDUM

20-Aug-2011

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

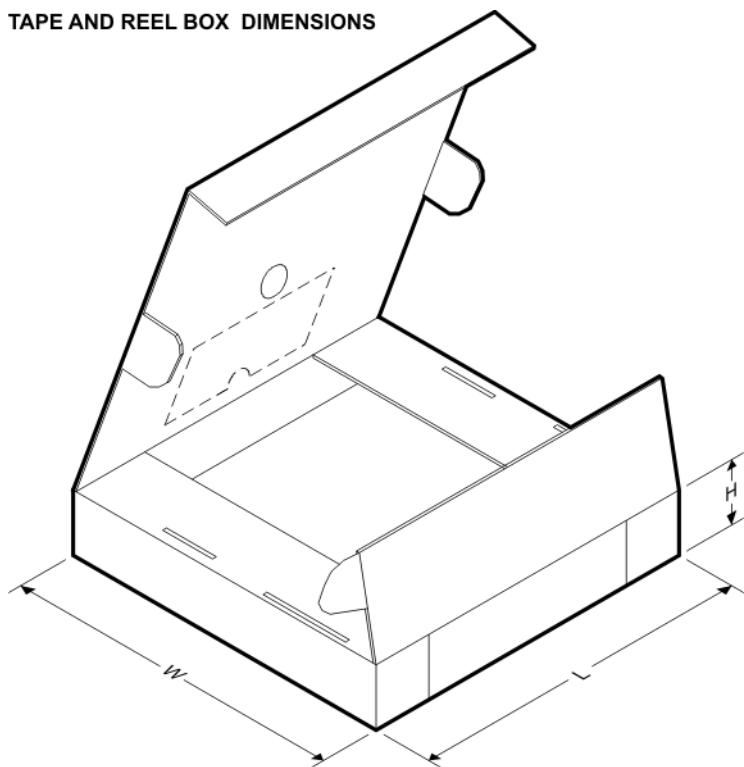
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TRS222CDWR	SOIC	DW	18	2000	330.0	24.4	10.9	12.0	2.7	12.0	24.0	Q1
TRS222IDWR	SOIC	DW	18	2000	330.0	24.4	10.9	12.0	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

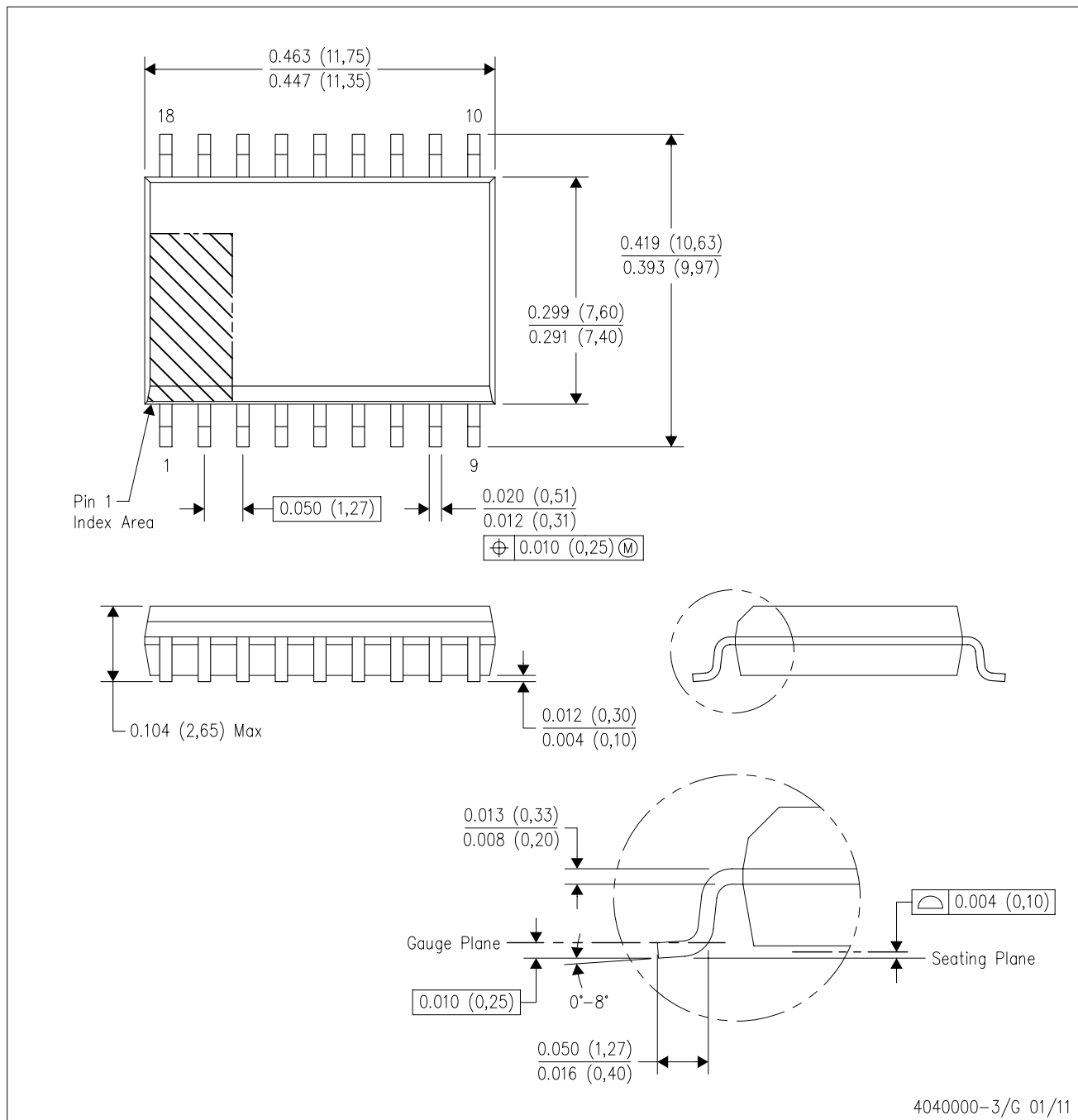


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TRS222CDWR	SOIC	DW	18	2000	370.0	355.0	55.0
TRS222IDWR	SOIC	DW	18	2000	370.0	355.0	55.0

DW (R-PDSO-G18)

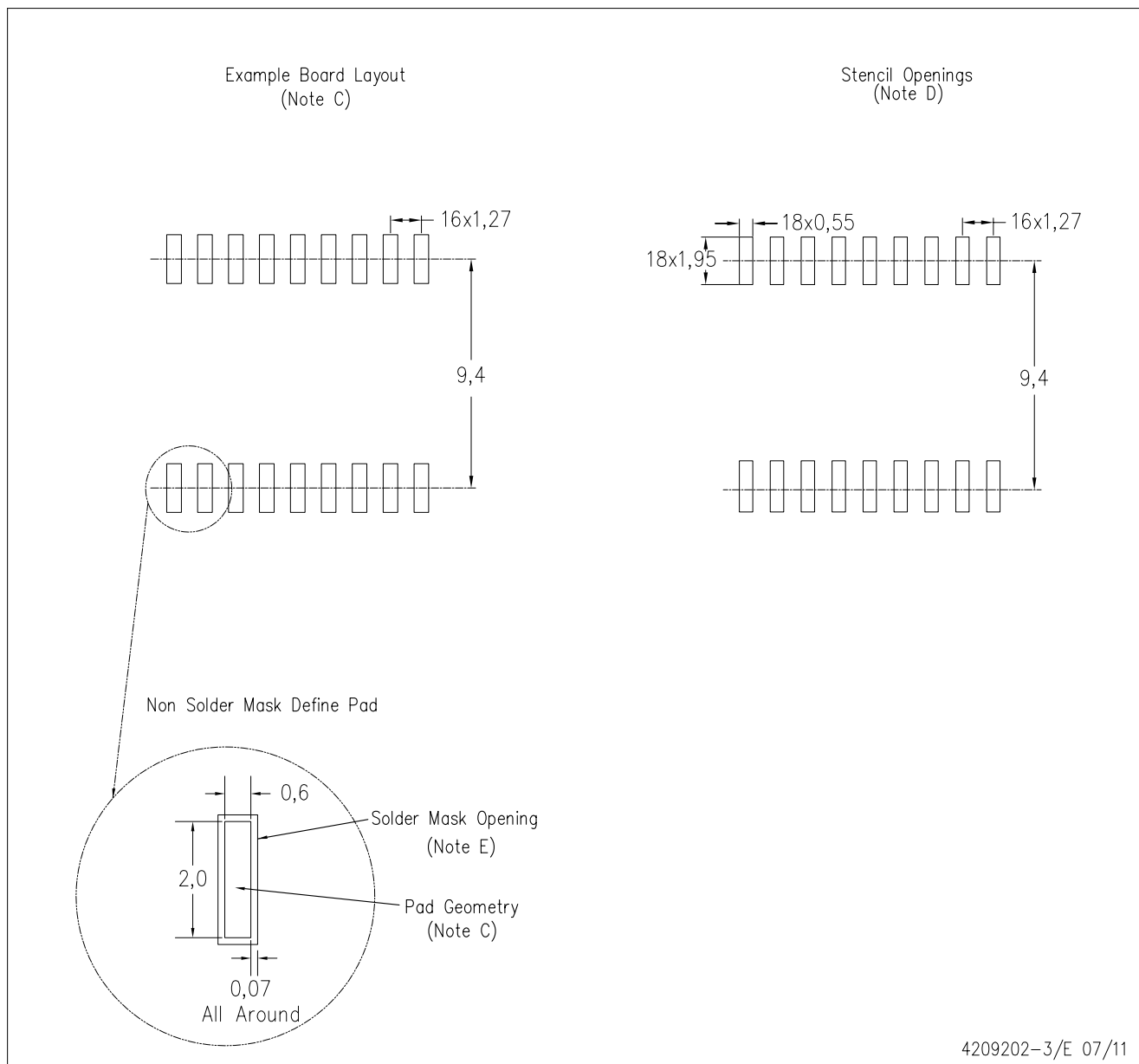
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed $0.006 (0,15)$.
 - Falls within JEDEC MS-013 variation AB.

DW (R-PDSO-G18)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2012, Texas Instruments Incorporated